

Figure 1. Comparison of the thickness development for the thermal and plasma-enhanced ALD process monitored by real-time spectroscopic ellipsometry.

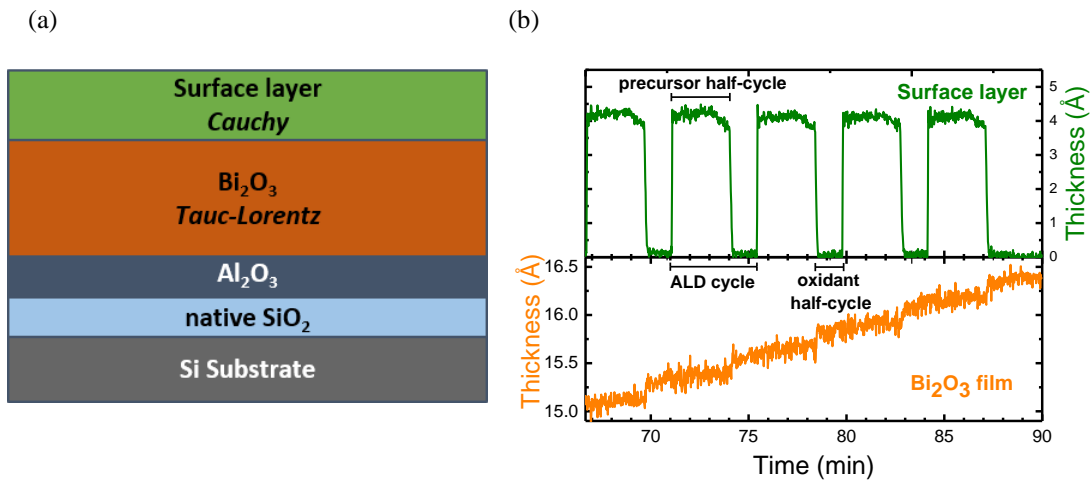


Figure 2. a) Schematic representation of the double-layer model. b) Thickness of the Bi_2O_3 film and surface layer monitored real time during ALD growth of Bi_2O_3 .